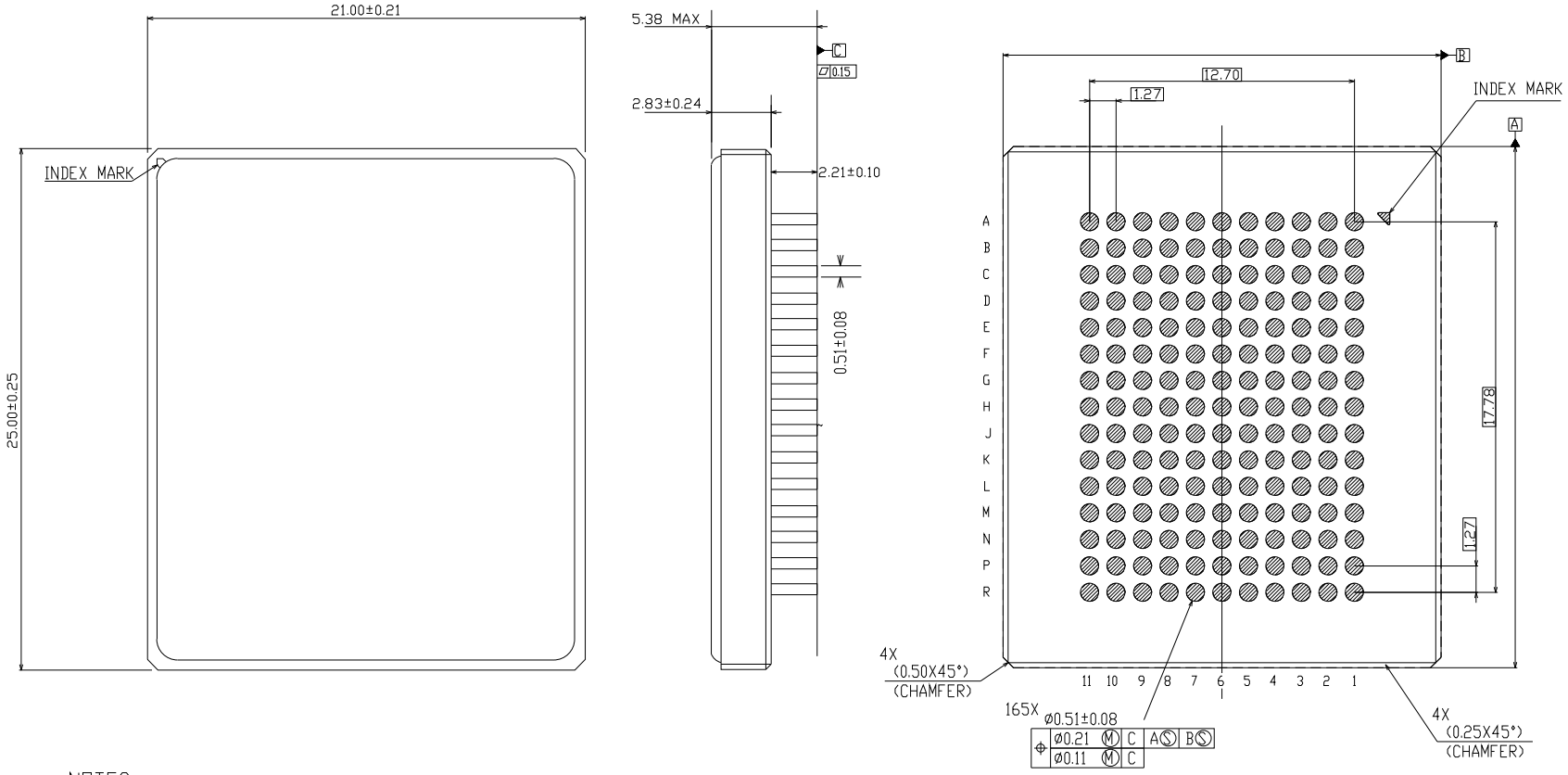
Please note that Cypress is an Infineon Technologies Company.
The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content
The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers
Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.



NOTES:

1. JEDEC REFERENCE : MO-158 VAR BE-1
2. ALL DIMENSIONS ARE IN MILLIMETERS

CYPRESS
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TITLE 165 CERAMIC COLUMN GRID ARRAY (CCGA)
21 X 25mm PACKAGE OUTLINE

DWG NO. 001-58969 | REV *E

SCALE: 1:1 | SHEET 1 OF 2

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PACKAGE CODE(S) | GC165 / GD165

REVISIONS			
REV.	ECN NO.	ORIG. OF CHANGE	DESCRIPTION OF CHANGE
**	2864590	JVP	CREATED DWG
*A	2930782	JVP	COMPLETE REDRAW. CHANGE PACKAGE OUTLINE DIMENSION FROM 18.5X21mm TO 21X25mm. UPDATE SPEC TITLE.
*B	3140952	MLA	REDRAW TO ADD LID.
*C	3171049	MLA	Add # of sheets in lower right corner.
*D	3901395	MLA	Change to new POD format.
*E	5051811	CMG	CHANGED SOLDER COLUMN DIAMETER FROM 0.51 +/- 0.05 MM TO 0.51 +/- 0.08 MM

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21 X 25mm PACKAGE OUTLINE

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SCALE: 1:1 | SHEET 2 OF 2